

Notice of References Cited

 Application/Control No.
 09/737,397

 Applicant(s)/Patent Under
 Reexamination
 TSUCHIYA ET AL.

 Examiner
 Maria Guerrero

 Art Unit
 2822

Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-6,140,225	10-0200	Usami et al.	438/637
	B	US-5,959,359	09-1999	Tsuchiya	257/766
	C	US-5,854,145	12-1998	Chandler et al.	442/59
	D	US-4,892,612	01-1990	Huff	438/693
	E	US-4,414,125	11-1983	Keil, deceased et al.	252/75
	F	US-			
	G	US-			
	H	US-			
	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N	WO 00/52230	09-2000	US	Kyle	C23F 11/10
	O					
	P					
	Q					
	R					
	S					
	T					

NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Yasutaka et al. (JP 08083780) (Translation)
	V	Hayasaki et al. "A new two-step metal-CMP technique for a high performance multilevel interconnects featured by Al and "Cu in low E, organic film" metallizations", 1996, IEEE, pages 88-89.
	W	
	X	

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
 Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.